a solder containing at least two components with at least two metal-containing constituents including a first constituent X being formed of a precious metal and a second constituent Y being consumed during a soldering operation by one of reacting and being dissolved in materials which are to be joined, and said solder having a hypereutectic concentration of said second constituent Y;

a substrate; and

a semiconductor chip secured to said substrate by one of alloying and brazing using said solder,

said solder containing a gold-tin compound (AuSn) with a hypereutectic Sn concentration and forming a layer having a thickness of from about 1 μm to about 2 μm.

Please Add the Following New Claim:

17. The semiconductor component according to claim 15, wherein said solder has a composition by weight of said first constituent X to said second constituent Y of 70 to 30.